

## C0603C131G2TACTU

Aliases (C0603C131G2TAC7867)

SMD Comm X8G HT150C, Ceramic, 130 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	3.7 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm
Packaging Specifications	

Specifications		
Capacitance	130 pF	
Measurement Condition	1 MHz 1.0Vrms	
Tolerance	2%	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
Dissipation Factor	0.1% 1 MHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

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Packaging	T&R, 180mm, Paper Tape	Reference to +25°C ar Applied (TCC)
Packaging Quantity	4000	Dissipation Factor
		Bissipation ractor

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